High Speed Direct Current Copper Electroplating Technology

高速直流电镀铜制程

COPPER GLEAM™ ST-920 Acid Copper

Consistently excellent through hole and microvia conformal plating performance on a vertical hoist DC plating process.

Wide effective current density range (10 – 35 A/ft²) with soluble anode.

在直流垂直电镀制程上，具有稳定且优异的通/盲孔贯孔能力。

搭配可溶性阳极，可操作电流密度范围大 (10 – 35 A/ft²) 。

Advantages of COPPER GLEAM™ ST-920 Acid Copper
COPPER GLEAM™ ST-920 具备以下优越的特性

- Excellent throwing power on through hole and microvia over high current density
  在高电流下仍具备优异的通孔与盲孔贯孔能力
- Superior panel plating distribution
  良好的电镀均匀度
- Compatibility with both panel and pattern plating process
  可适用于全板或二次铜电镀制程
- Easily analyzed and controlled by conventional CVS
  控制简易，并可用CVS分析控制
- Good thermal reliability
  卓越的耐热信赖度

Microvia Conformal Plating

Figure 1: Microvia conformal plating
- 100 µm ϕ x 60 µm BMV-Eless
- Throwing Power = 91%

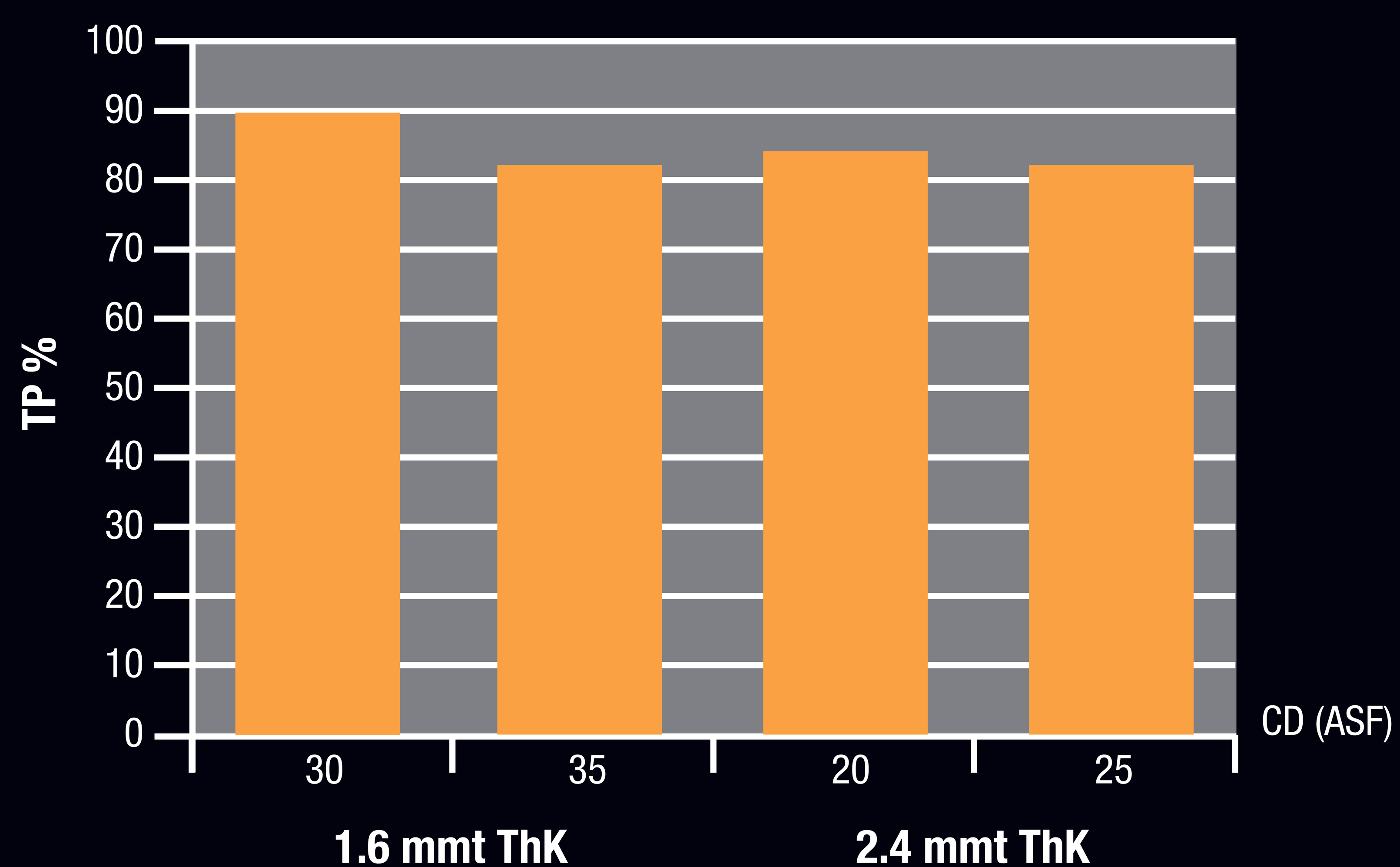

Figure 2: Through Hole (TP%) at 1.6 &2.4 mmt board thickness

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